



### Features 特性

- Low Thermal Resistance 低热阻
- Low Viscosity 低粘度
- High Reliability 高可靠性
- Easy Printing 易印刷

### Applications 产品应用

- Laptop CPU 笔记本电脑 CPU
- Communication equipment 通讯设备
- Power supply controller 电源控制系统
- ADAS 智能驾驶系统

**Thermal TIG0600E** 是一种具有低粘度，低热阻的导热硅脂，可采用印刷或点胶的方式涂覆在发热器件或者散热器表面，装配后可以跟界面形成良好的润湿，降低系统的接触热阻，从而提高散热效率。

**Thermal TIG0600E** is a kind of thermal grease material with low viscosity and low thermal resistance. The material can be applied on heating devices and heat spreader surfaces by printing or dispensing. Due to good wetting between the interfaces after assembly, the contact thermal resistance will be substantially reduced to improve heat dissipation efficiency.

Property 特性	Typical Value 典型值	Unit 单位	Test Method 测试方法
<b>Composition</b> 主要成分	Silicone Filled with Thermal Powder 硅胶&导热粉体	—	—
<b>Color</b> 颜色	Gray 灰色	—	Visual 目视
<b>Thermal Conductivity</b> 导热系数	6.0	W/m·K	ASTM D5470
<b>Thermal Resistance</b> 热阻	0.068 @ 40Psi	°C.cm <sup>2</sup> /W	ASTM D5470
<b>Bond-line Thickness (BLT)</b> 界面结合厚度	25	μm	—
<b>Viscosity</b> 粘度@1s <sup>-1</sup>	380	Pa.s	ASTM D2196
<b>Density</b> 密度	2.6	g/cm <sup>3</sup>	ASTM D792
<b>Temperature Range</b> 耐温范围	-40 - 150	°C	—
<b>RoHS Compliance</b> 合规性	YES	—	—
<b>Shelf Life</b> 保存期	6	month	25±5°C ≤50% RH 未启封

All technical information stated in this technical data have been confirmed that all the technical parameters are reliable after harsh testing and evaluation of the products. Before you use our products, please carefully evaluate and decide whether the product meets your requirement and you need to take all the risks and responsibilities to use.

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